

Amendments to the Claims:

This listing of the claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1-19 (Canceled)

20 (New): A micro terminal with electrical conduction between said micro terminal and an electrode of an electronic device or an inspection device, comprising a columnar contactor in contact with the electrode, wherein

said contactor has a plate-shaped spring structure that is elastically deformed by being pressed against the electrode, a perimeter portion of said spring structure has a tubular ring structure, and said contactor has a protrusion protruding outwardly at its end in contact with the electrode, and

said protrusion is shaped to have a part of a sphere or a paraboloid of revolution.

21 (New): The micro terminal according to claim 20, wherein said contactor has a spiral spring structure.

22 (New): The micro terminal according to claim 20, wherein said micro terminal has said contactor at each of opposing ends in contact with the electrode.

23 (New): The micro terminal according to claim 20, wherein said protrusion has a V-shaped groove opening toward the direction in which said protrusion protrudes.

24 (New): The micro terminal according to claim 20, wherein said micro terminal includes nickel or a nickel alloy.

25 (New): The micro terminal according to claim 20, wherein said micro terminal has a coat layer including a precious metal or an alloy of a precious metal or polytetrafluoroethylene gold.

26 (New): A contact sheet including the micro terminal according to claim 20, having a hollow electrode penetrating the sheet in a thickness direction and said contactor on said hollow electrode, wherein said hollow electrode has a hollow portion for a spring of said contactor to make a stroke.

27 (New): The contact sheet according to claim 26, wherein said hollow electrode and said contactor are joined by resistance welding.

28 (New): A socket for inspection including the micro terminal according to claim 20, wherein said socket is used for inspection of semiconductor in land grid array arrangement.

29 (New): An inspection device including the socket according to claim 28.

30 (New): A method of inspecting semiconductor using the socket according to claim 28.

31 (New): A connector for installation including the micro terminal according to claim 20, wherein said connector is connected to a land electrode.

32 (New): An electronic device including the connector according to claim 31.